MMBTA06LT1 is a Preferred Device

Driver Transistors

NPN Silicon

Features

• Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage MMBTA05LT1 MMBTA06LT1	V _{CEO}	60 80	Vdc
Collector – Base Voltage MMBTA05LT1 MMBTA06LT1	V _{CBO}	60 80	Vdc
Emitter - Base Voltage	V _{EBO}	4.0	Vdc
Collector Current – Continuous	Ic	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W	
Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W	
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C	

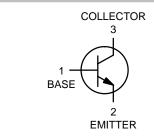
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



ON Semiconductor®

http://onsemi.com

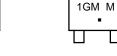




SOT-23 CASE 318 STYLE 6

MARKING DIAGRAMS





MMBTA05LT1

MMBTA06LT1

1H, 1GM = Specific Device Code

M = Date Code= Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

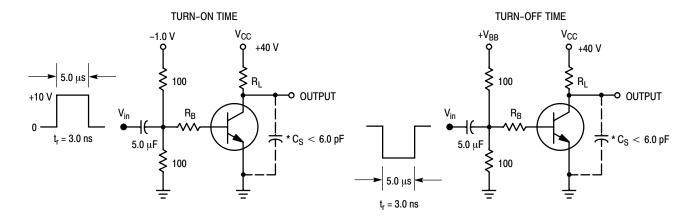
See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 3) (I _C = 1.0 mAdc, I _B = 0)	MMBTA05 MMBTA06	V _{(BR)CEO}	60 80	_ _	Vdc
Emitter – Base Breakdown Voltage ($I_E = 100 \mu Adc, I_C = 0$)		V _{(BR)EBO}	4.0	-	Vdc
Collector Cutoff Current (V _{CE} = 60 Vdc, I _B = 0)		I _{CES}	-	0.1	μAdc
Collector Cutoff Current $(V_{CB} = 60 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 80 \text{ Vdc}, I_E = 0)$	MMBTA05 MMBTA06	I _{CBO}	- -	0.1 0.1	μAdc
ON CHARACTERISTICS		•			
DC Current Gain ($I_C = 10 \text{ mAdc}$, $V_{CE} = 1.0 \text{ Vdc}$) ($I_C = 100 \text{ mAdc}$, $V_{CE} = 1.0 \text{ Vdc}$)		h _{FE}	100 100	_ _	_
Collector – Emitter Saturation Voltage (I _C = 100 mAdc, I _B = 10 mAdc)		V _{CE(sat)}	_	0.25	Vdc
Base – Emitter On Voltage (I _C = 100 mAdc, V _{CE} = 1.0 Vdc)		V _{BE(on)}	-	1.2	Vdc
SMALL-SIGNAL CHARACTERISTICS		•	-		•
Current – Gain – Bandwidth Product (Note 4) (I _C = 10 mA, V _{CE} = 2.0 V, f = 100 MHz)		f _T	100	_	MHz

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%. 4. f_T is defined as the frequency at which $|h_{fe}|$ extrapolates to unity.



^{*}Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 1. Switching Time Test Circuits

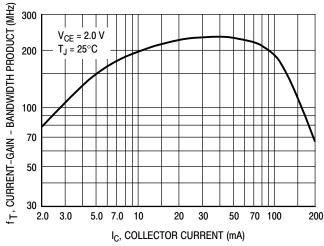


Figure 2. Current-Gain — Bandwidth Product

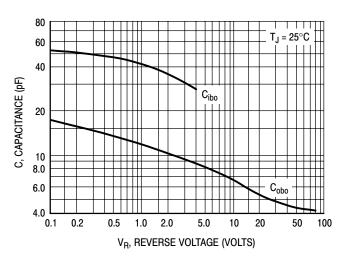


Figure 3. Capacitance

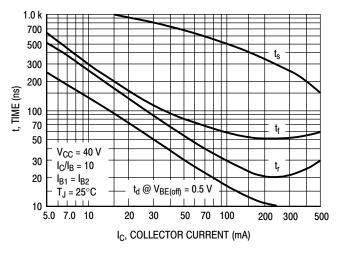


Figure 4. Switching Time

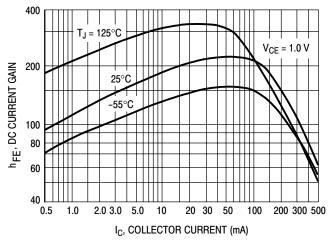


Figure 5. DC Current Gain

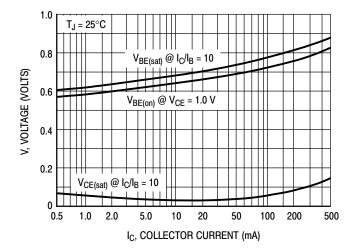
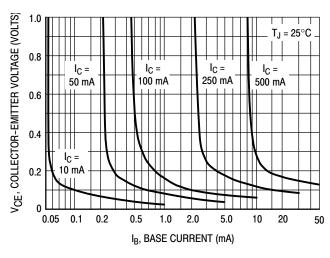


Figure 6. "ON" Voltages



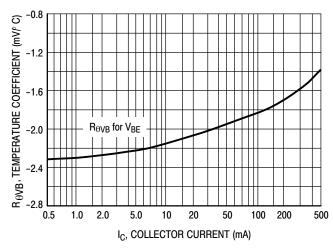


Figure 7. Collector Saturation Region

Figure 8. Base–Emitter Temperature Coefficient

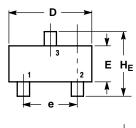
ORDERING INFORMATION

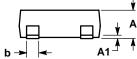
Device	Package	Shipping [†]		
MMBTA05LT1	SOT-23	3000 / Tape & Reel		
MMBTA05LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBTA05LT3	SOT-23	10,000 / Tape & Reel		
MMBTA05LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel		
MMBTA06LT1	SOT-23	3000 / Tape & Reel		
MMBTA06LT1G	SOT-23 (Pb-Free)	3000 / Tape & Reel		
MMBTA06LT3	SOT-23	10,000 / Tape & Reel		
MMBTA06LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel		

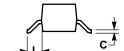
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AL**







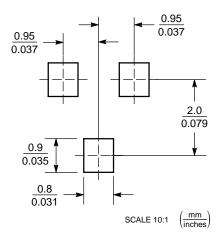
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. 318–01 THRU –07 AND –09 OBSOLETE, NEW STANDARD 318–08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

PIN 1. BASE 2. EMITTER 3. COLLECTO COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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